

FEATURES AND SPECIFICATIONS

Features and Benefits

- 10 to 64 circuits
- Tin plated on solder tail
- Complies with industry standard DIN 41654
- Polarized
- Selective Gold plating options for contacts
- Eject levers allow end-to-end stacking with or without strain relief with no loss of board space

Reference Information

Packaging: Tray
Designed In: Millimeters
Mates With: [5320](#)

Electrical

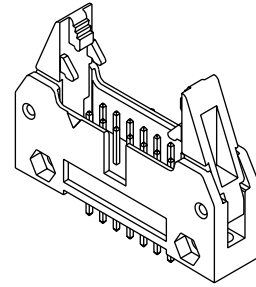
Voltage: 250V
Current: 1.0A
Contact Resistance: 20mΩ max.
Dielectric Withstanding Voltage: 500V
Insulation Resistance: 1000 MΩ min.

Physical

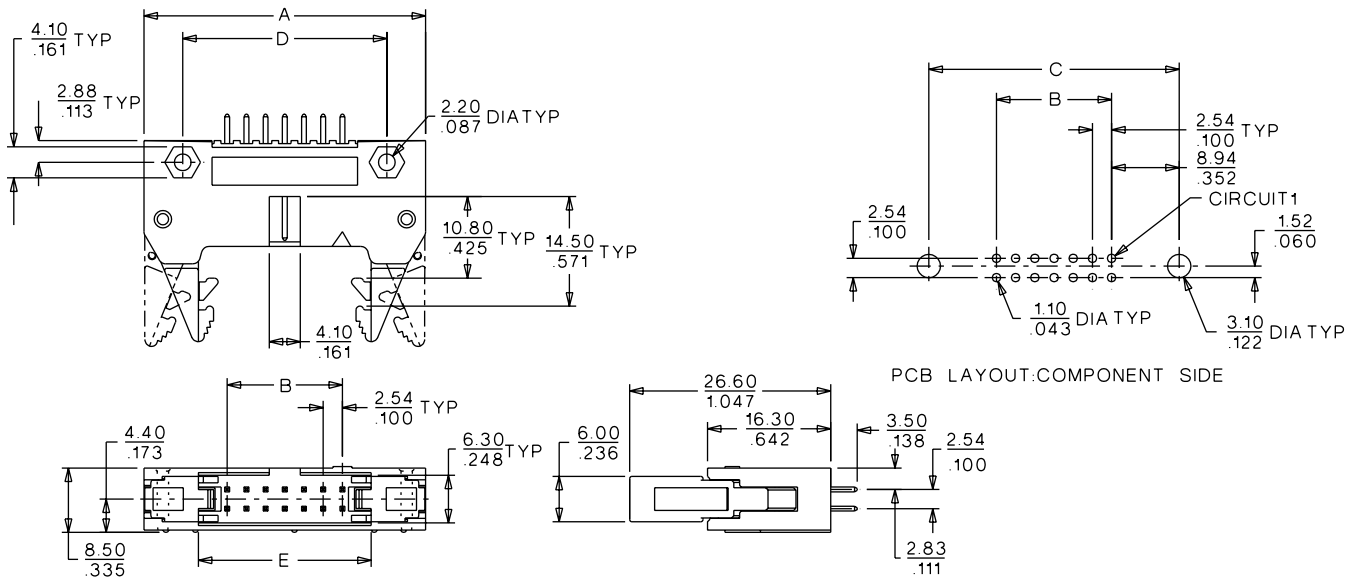
Housing: Glass-filled PBTP
Contact: Brass
Operating Temperature: -40 to +105°C

molex® 2.54mm (.100) Pitch QF 50™ Shrouded Header

5576 Vertical With Eject Levers



CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.			Dimension				
	Plating NBGS1	Plating NBGS2	Plating NBT2	A	B	C	D	E
10	39-27-1103	39-27-1104	39-28-5105	32.16 (1.266)	10.16 (0.400)	28.04 (1.104)	21.94 (0.864)	17.76 (0.700)
14	39-27-1143	39-27-1144	39-28-5145	37.24 (1.466)	15.24 (0.600)	33.12 (1.304)	27.02 (1.064)	22.84 (0.900)
16	39-27-1163	39-27-1144	39-28-5165	39.78 (1.566)	17.78 (0.700)	35.66 (1.404)	29.56 (1.164)	25.38 (1.000)
20	39-27-1203	39-27-1144	39-28-5205	44.86 (1.766)	22.86 (0.900)	40.74 (1.604)	34.64 (1.364)	30.46 (1.200)
26	39-27-1263	39-27-1154	39-28-5265	52.48 (2.066)	30.48 (1.200)	48.36 (1.904)	42.26 (1.664)	38.08 (1.500)
30	39-27-1303	39-27-1154	39-28-5305	57.56 (2.266)	35.56 (1.400)	53.44 (2.104)	47.34 (1.864)	43.16 (1.700)
34	39-27-1343	39-27-1154	39-28-5345	62.64 (2.466)	40.64 (1.600)	58.52 (2.304)	52.42 (2.064)	48.24 (1.900)
40	39-27-1403	39-27-1154	39-28-5405	70.26 (2.766)	48.26 (1.900)	66.14 (2.604)	60.04 (2.364)	55.86 (2.200)
50	39-27-1503	39-27-1154	39-28-5505	82.96 (3.266)	60.96 (2.400)	78.84 (3.104)	72.74 (2.864)	68.56 (2.700)
60	39-27-1603	39-27-1154		95.66 (3.766)	73.66 (2.900)	91.54 (3.604)	85.44 (3.364)	81.26 (3.200)
64	39-27-1643	39-27-1154		100.74 (3.966)	78.74 (3.100)	96.62 (3.804)	90.52 (3.564)	86.34 (3.400)

Plating NBGS1: 39μ" (1μm) min. Nickel underplate. Contact area: 0.1μm min. Gold.
Solder area: 3μm min. Tin/Lead.

Plating NBGS2: 39μ" (1μm) min. Nickel underplate. Contact area: 0.76μm min. Gold.
Solder area: 3μm min. Tin/Lead.

Plating NBT2: 20μ" (0.5μm) min. Nickel underplate. Contact and solder area: 39μ" (1μm) min. Tin.